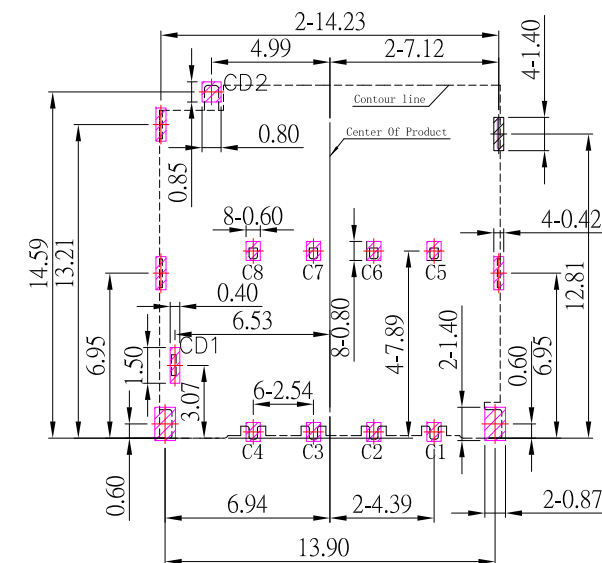
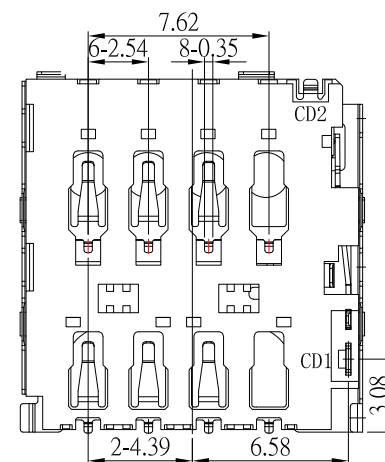
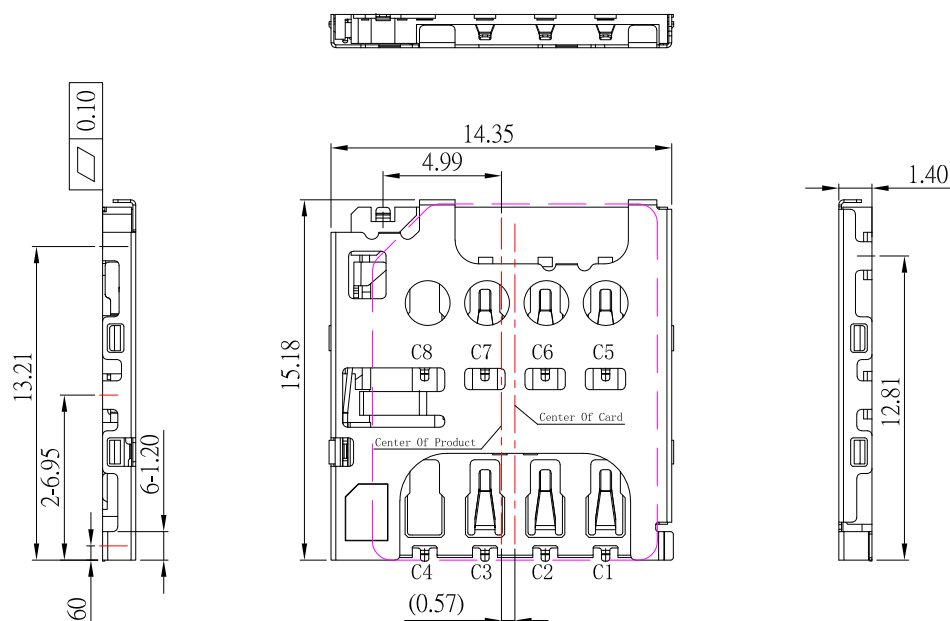
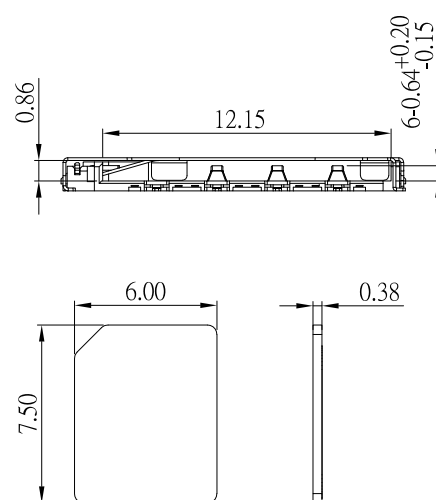
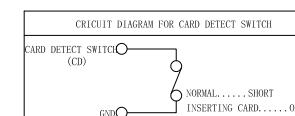




P.C.B LAYOUT



PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved
CD1	Detect Switch
CD2	Detect Switch

NOTES:

1) MATERIAL:

1.1 HOUSING: LCP

1.2 CONTACT: PHOSPHOR BRONZE

1.3 SHELL: SUS

2) *FINISH* :

2.1 CONTACT: PLATED GOLD IN MATING AREA ;

GOLD PLATED ON SOLDER BALLS :

NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3) ELECTRICAL CHARACTERISTICS

3.1 RATING CURRENT: 0.5 A

3.2 RATING VOLTAGE: 30V DC

3.3 CONTACT RESISTANCE: 100 mΩ MAX

3.4 INSULATION RESISTANCE:1000M Ω MIN

4.5 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC

4.6 OPERATING TEMPERATURE: -40°C ~ +75°C

				CONTACT 建倚科技股份有限公司 CONTACT TECHNOLOGY CORP. TOLERANCE UNLESS OTHERWISE STATED : Up to 5 Above 5 ~ 15 Above 15 ~ 30 Above 30 ~ 50 Angle ±0.2 ±0.3 ±0.4 ±0.5 ±0.3 3RD. ANGEL'S  UNITS MM	DRAWN BY: DATE		MAT'L		TITLE	CONNECTOR	
					Jack Lu	07/29/25	FINISH		MODLE	MICRO SIM CARD CONNECTOR 8PIN	
					Jacky Chen	07/29/25				NO-PUSH H1.40mm	
					APPROVED BY: DATE		SCALE	1 : 1	DWG NO.	MSIM-008-S304	SIZE
ITEM NO.	DESCRIPTION	DRAWN	DATE	Tony Kao		07/29/25	SHEET NO.	1 of 1	PART NO.	MSIM-008-S304	VER
										R	